



Final Product Change Notification

201607032F01

Issue Date: 25-Jul-2016
Effective Date: 07-Nov-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input checked="" type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage

Release of additional products from Vanguard as a 2nd source for Trench 6 MOSFETS

Details of this Change

NXP are notifying customers of the release of additional products from Vanguard International Semiconductors, Hsinchu, Taiwan as a second source for the supply of TrenchMOS Generation 6 MOSFET products. NXP will continue to use NXP Manchester, UK, for wafer diffusion along with Vanguard. Assembly and final test remain unchanged at NXP Semiconductors, Cabuyao, Philippines

Why do we implement this Change

To ensure production capacity for TrenchMOS Generation 6 products.

Identification of Affected Products

Top side marking

The manufacturing sites for both diffusion and assembly are identified on both the outerbox and the device top side marking. The diffusion code for Manchester will be shown as 'E' and Vanguard by 'r'.

Product Availability

Sample Information

Samples are available from 17-Oct-2016

Production

Planned first shipment 28-Nov-2016

Impact

no impact to the product's functionality anticipated.
No change to product structure or electrical characteristics.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

N/A

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 24-Aug-2016.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

e-mail address powermos.pcn@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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NXP Semiconductors

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
PSMN1R3-30YL,115	934063811115	PSMN1R3-30YL	9656 TRENCH 6	SOT1023	4 LEADS	RFS	BL POWER MOS
PSMN1R2-25YL,115	934063812115	PSMN1R2-25YL	9656 TRENCH 6	SOT1023	4 LEADS	RFS	BL POWER MOS